

## 2016 Editorial Calendar

### July • August

Materials development of SiP & IoT	<ul style="list-style-type: none"><li>• <b>ICEPT 2016</b> Wuhan, China (Aug 16-19)</li><li>• <b>SEMICON Taiwan</b> Taipei, Taiwan (Sept 7-9)</li><li>• <b>BiTS China 2016</b> Suzhou, China (Sept 13)</li><li>• <b>ESTC</b> Grenoble, France (Sept 13-16)</li><li>• <b>MEPTEC Medical Electronics Symposium</b> Portland, OR (Sept 14-16)</li><li>• <b>SEMI European MEMS Summit</b> Stuttgart, Germany (Sept 15-16)</li></ul>
Silicon 3D Integration for small power devices	
Solder reliability	
Environmental impact of packaging processes	
MEMS challenges in the IoT era	
Materials for test sockets	
Direct bonding technology	
Warpage in FCBGAs	
International Directory of Bonding Equipment for 2.5D and 3D Assembly	
Ad Space Close Jun 24 - Ad Materials Close Jul 1	

### September • October

Panel Level Packaging for FO-WLP	<ul style="list-style-type: none"><li>• <b>IMAPS 2016</b> Pasadena, CA (Oct 11-13)</li><li>• <b>ICPT 2016</b> Beijing, China (Oct 17-19)</li><li>• <b>IWLPC-International Wafer-Level Packaging Conference &amp; Exhibition</b> San Jose, CA (Oct 18-20)</li><li>• <b>SEMICON Europa</b> Grenoble, France (Oct 25-27)</li></ul>
Probe card inspection	
Trends in TSV technologies	
Market update on multi-die ICs	
Bonding / debonding for heterogeneous integration	
Hermetic CSP for MEMS	
LED packaging	
Micro testing thin die	
SiP	
Ad Space Close Sep 9 - Ad Materials Close Sep 16	

### November • December

FOWLP in the foundry	<ul style="list-style-type: none"><li>• <b>MEMS Executive Congress</b> Scottsdale, AZ (Nov 10-11)</li><li>• <b>MEPTEC Semiconductor Packaging Roadmap Symposium</b> San Jose, CA (Nov 14)</li><li>• <b>International Test Conference (ITC)</b> Fort Worth, TX (Nov 15-17)</li><li>• <b>SEMICON Japan</b> Tokyo, Japan (Dec 14-16)</li><li>• <b>3D ASIP Conference</b> Burlingame, CA (Dec 13-15)</li></ul>
3D TSV assembly	
Die stacking	
High-frequency test sockets	
Wafer-level test	
High performance photoresist for advanced packaging	
Dicing of silicon carbide power devices	
Glass for semiconductor/optoelectronics packaging	
Interconnects for MEMS & sensors	

For ad inquiries: [ads@chipscalereview.com](mailto:ads@chipscalereview.com) - For editorial inquiries [editor@chipscalereview.com](mailto:editor@chipscalereview.com)

Notes: Editorial calendar topics and distribution are subject to change without notice and are contingent on logistics and magazine production.

Haley Publishing Inc. 2016 All rights reserved. Rev: CSR-EC-101016